



US00D612343S

(12) **United States Design Patent**
Wei et al.

(10) **Patent No.:** **US D612,343 S**
(45) **Date of Patent:** **** Mar. 23, 2010**

(54) **HEAT DISSIPATION DEVICE**
(75) Inventors: **An-Chi Wei**, Miao-Li Hsien (TW);
Shan-Ju Lin, Miao-Li Hsien (TW)
(73) Assignee: **Foxsemicon Integrated Technology, Inc.**, Chu-Nan, Miao-Li Hsien (TW)

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(**) Term: **14 Years**

Primary Examiner—Selina Sikder

(21) Appl. No.: **29/339,851**

(74) *Attorney, Agent, or Firm*—Raymond J. Chew

(22) Filed: **Jul. 8, 2009**

(57) **CLAIM**

(30) **Foreign Application Priority Data**

The ornamental design for a heat dissipation device, as shown.

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DESCRIPTION

(51) **LOC (9) Cl.** **13-03**

FIG. 1 is a perspective view of a heat dissipation device showing our new design.

(52) **U.S. Cl.** **D13/179**

FIG. 2 is a front elevational view thereof.

(58) **Field of Classification Search** D13/179;
165/80.3, 104.33, 151, 122, 185; 257/706,
257/707, 718-722; 361/687, 695, 697, 700,
361/702, 704, 709, 710, 711, 719

FIG. 3 is a rear elevational view thereof.

See application file for complete search history.

FIG. 4 is a left-side, elevational view thereof.

FIG. 5 is a right-side, elevational view thereof.

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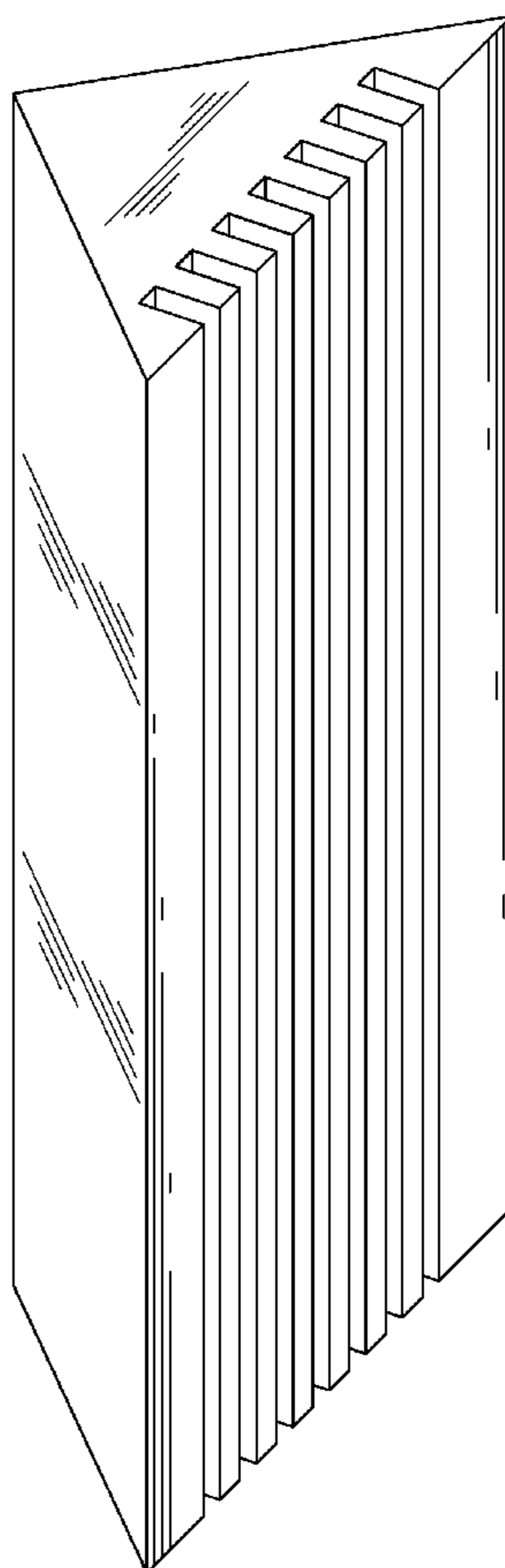
FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

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1 Claim, 7 Drawing Sheets



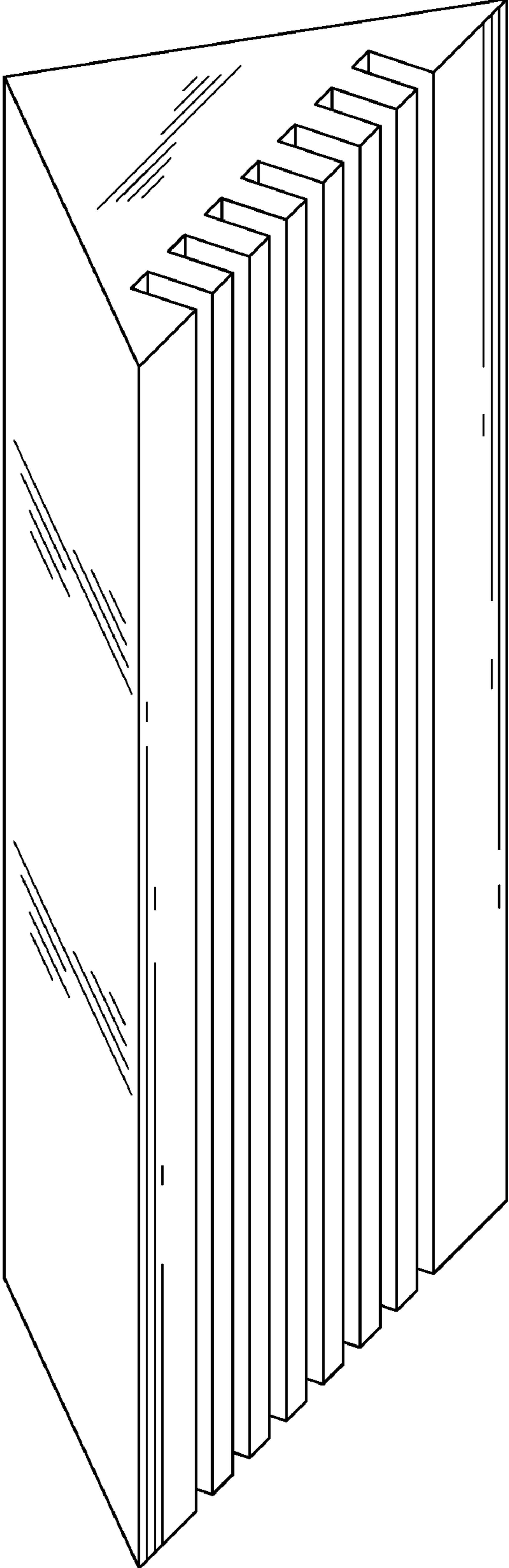


FIG. 1

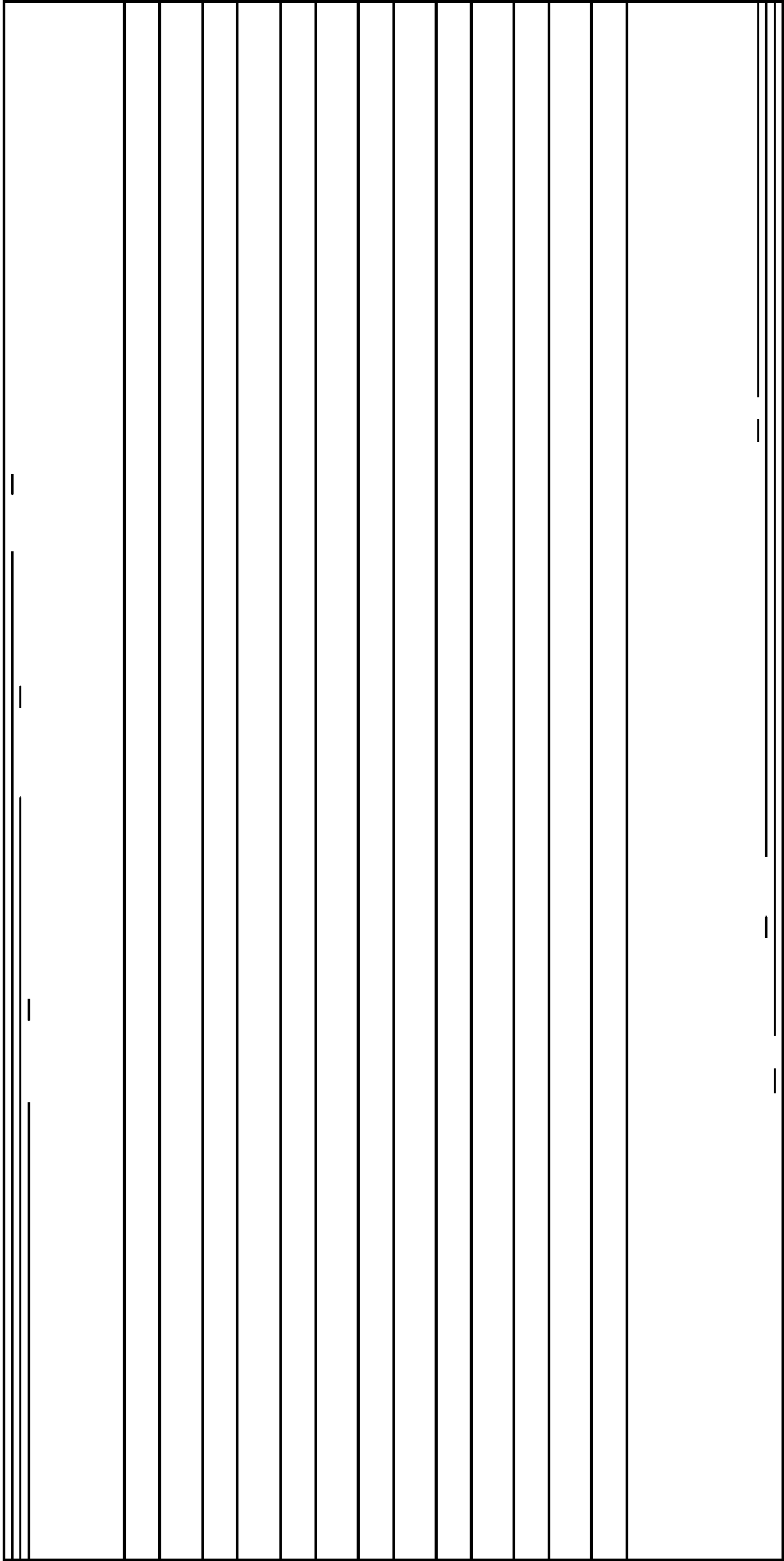


FIG. 2

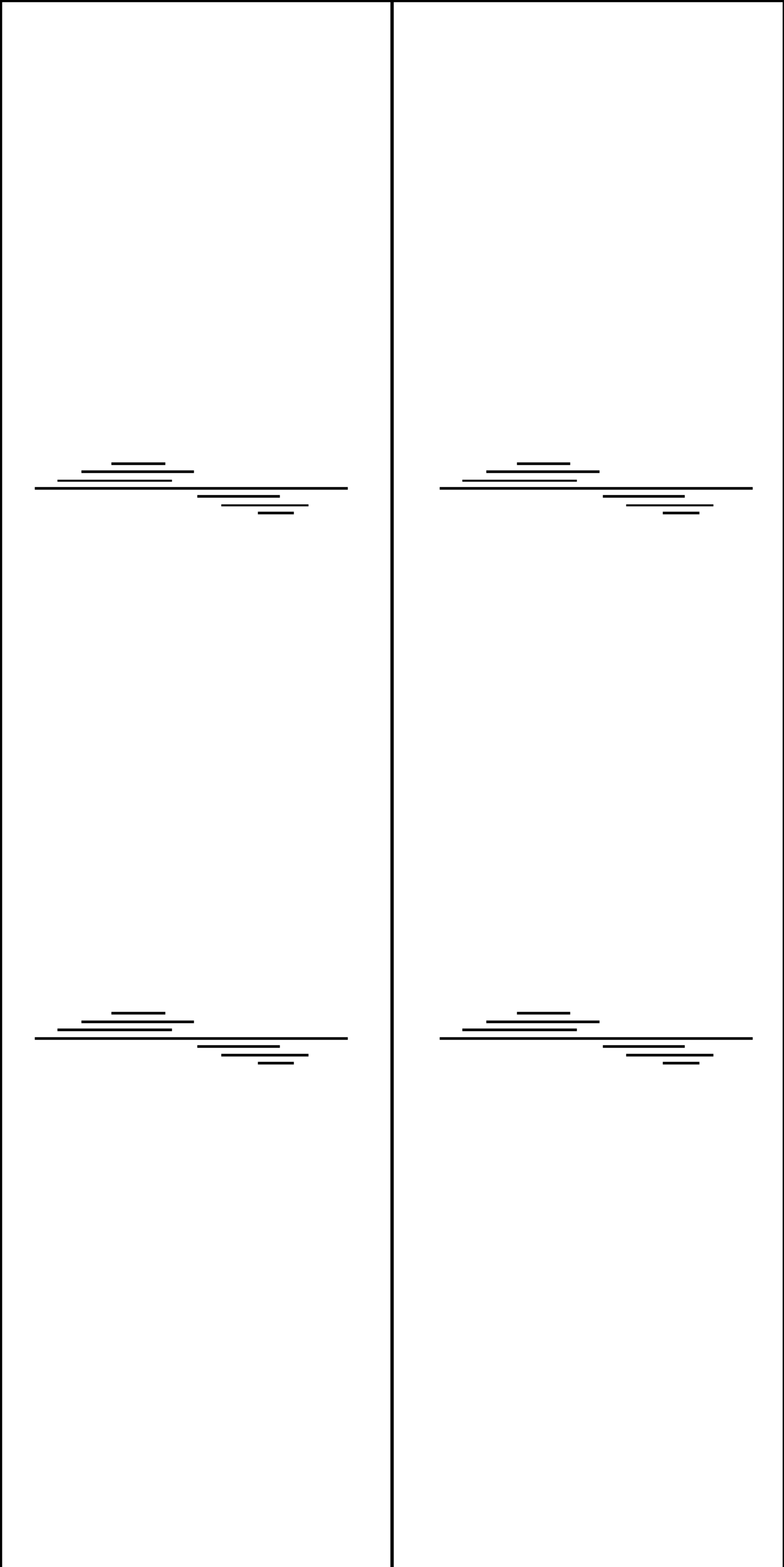


FIG. 3

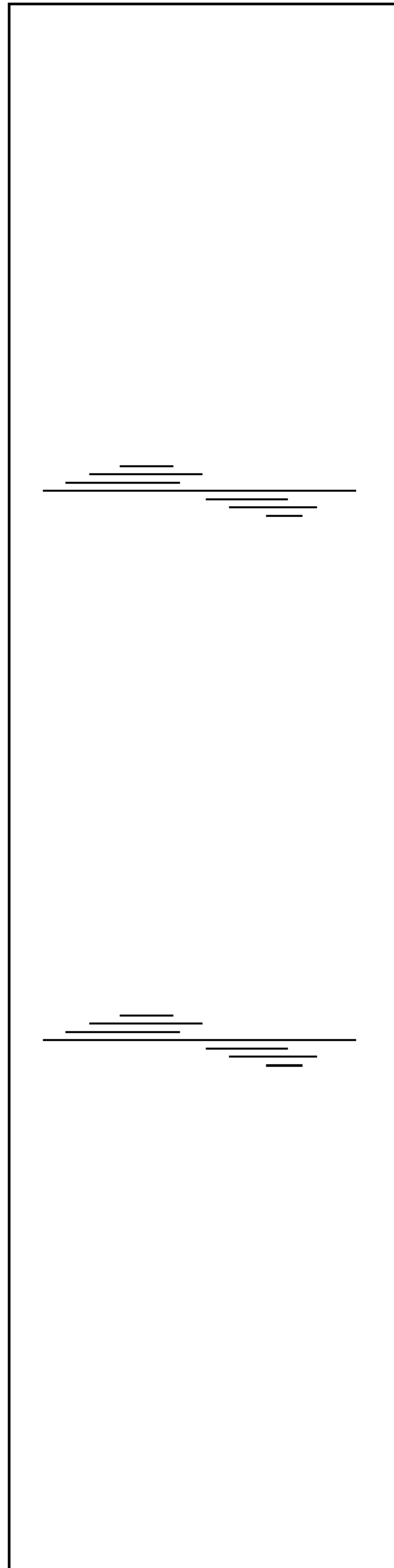


FIG. 4

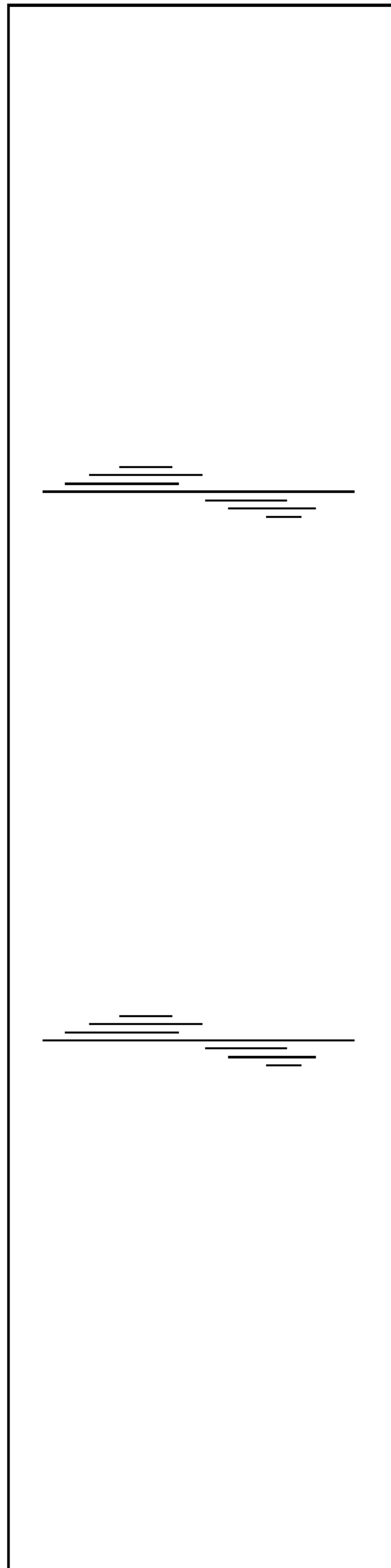


FIG. 5

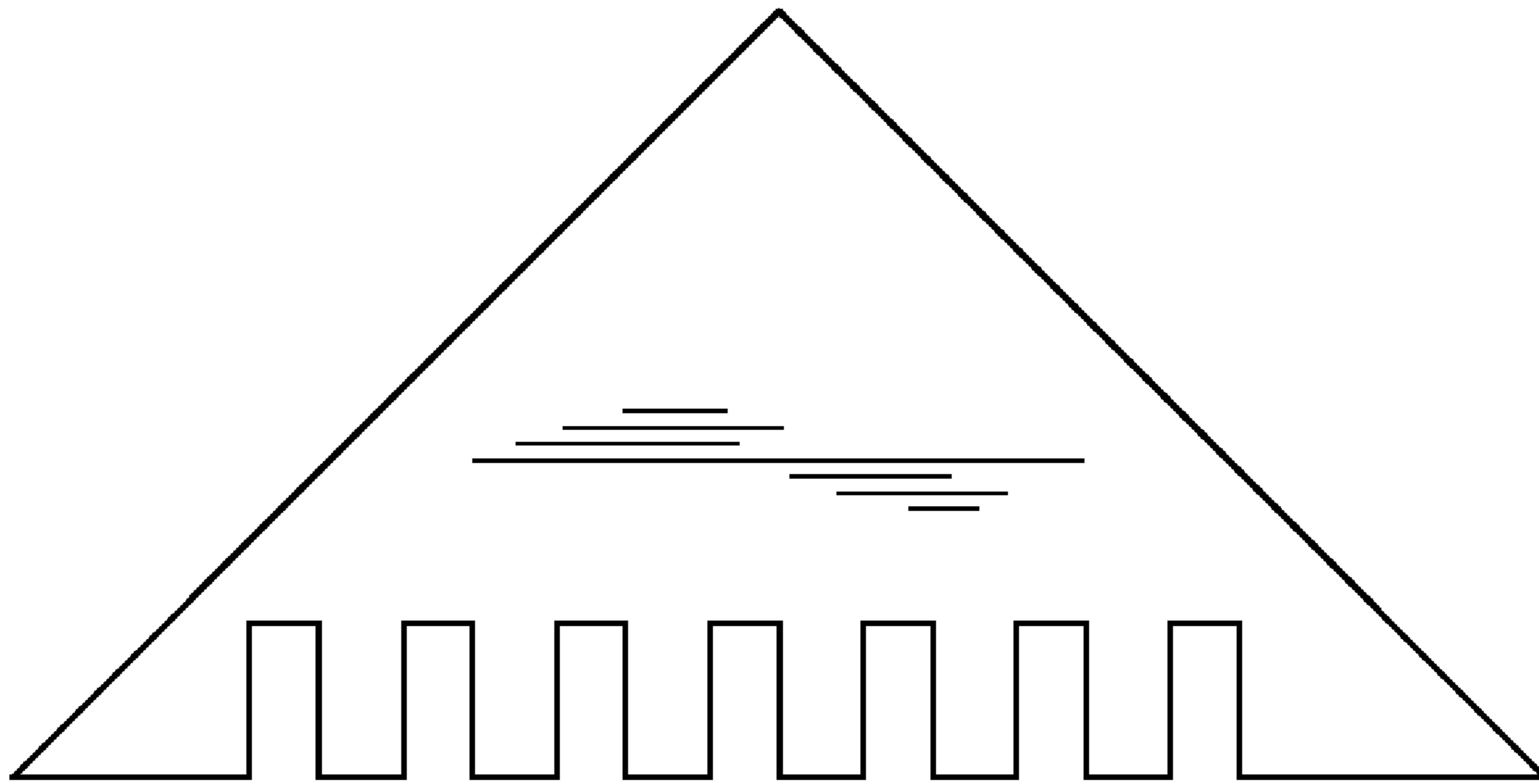


FIG. 6

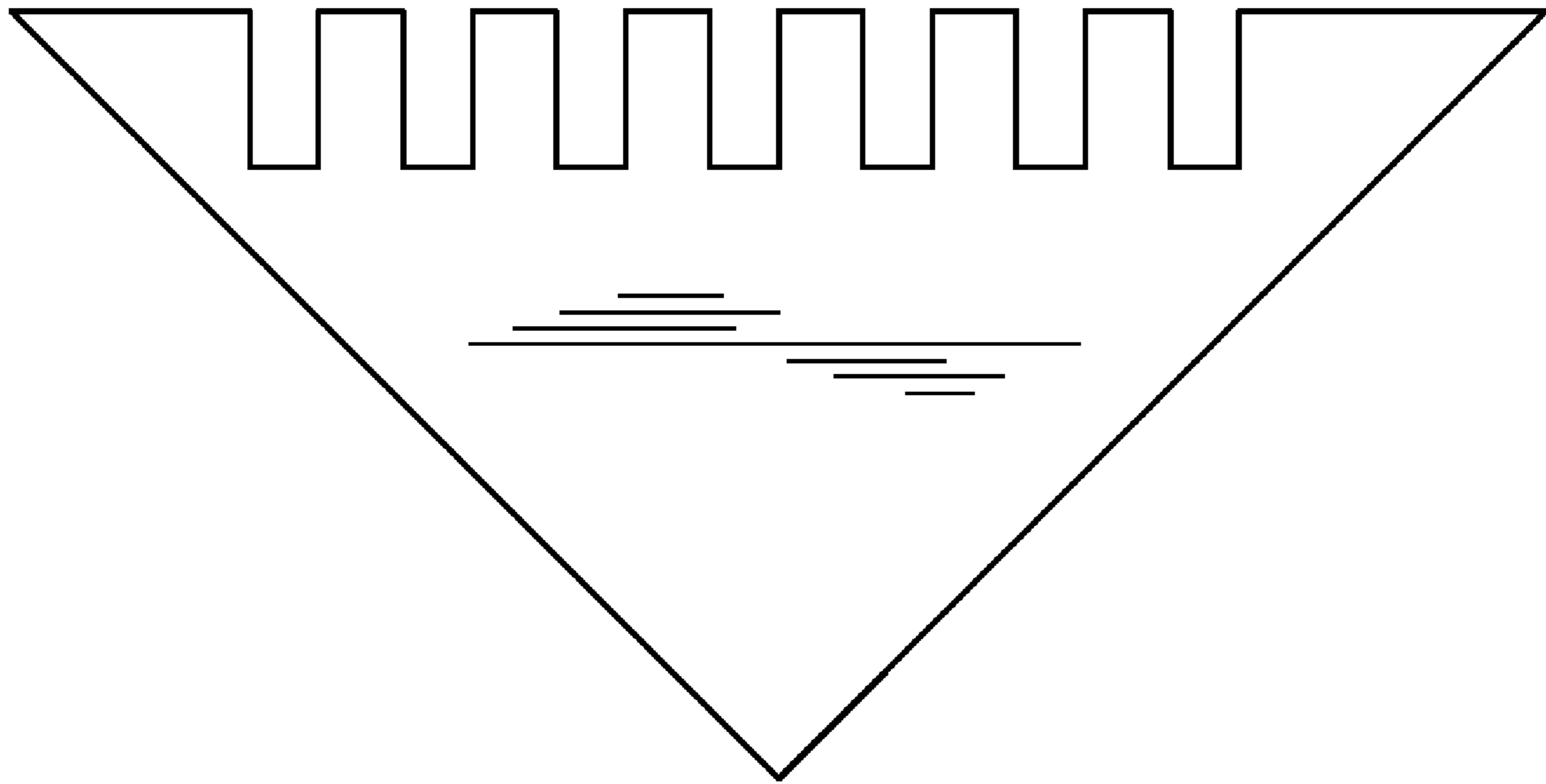


FIG. 7